

Appl. No.: 09/623,115  
Response dated January 22, 2004  
Reply to Office action of October 23, 2003

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-13 (cancelled)

Claim 14 (currently amended): A fiber-free molding composition comprising:

(a) a binder selected from the group consisting of an epoxide, a polyisocyanate, a furane-resin-free phenolic resin, and mixtures thereof; and

(b) a filler mixture containing:

(i) from about 20 to 90% by weight, based on the weight of the filler mixture,  
of an inorganic high-temperature-resistant filler; and

(ii) a heat-activatable swelling agent.

Claim 15 (previously presented): The composition of claim 14 wherein the filler mixture further comprises:

(iii) an adhesive;

(iv) a micropore-forming, high-temperature-resistant filler; and

(v) a grinding and/or anticaking agent.

Claim 16 (previously presented): The composition of claim 14 wherein the filler mixture has a pH of up to 7.5.

Claim 17 (previously presented): The composition of claim 15 wherein the filler mixture

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contains:

- (i) from 20 to 90% by weight of the inorganic high-temperature-resistant filler;
- (ii) from 1 to 30% by weight of the heat-activatable swelling agent;
- (iii) from 0.1 to 35% by weight of the adhesive;
- (iv) from 2 to 40% by weight of the micropore-forming, high-temperature-resistant filler; and
- (v) from 0.01 to 10% by weight of the grinding and/or anticaking agent, all weights being based on the total weight of the molding.

Claim 18 (previously presented): The composition of claim 14 further comprising a hardener.

Claim 19 (previously presented): The composition of claim 14 further comprising an emulsifier and a blowing agent.

Claim 20 (previously presented): The composition of claim 14 wherein the molding has a density of from 100 to 300 kg/m<sup>3</sup>.

Claim 21 (previously presented): A process for making a fiber-free molding composition comprising:

- (a) providing a binder selected from the group consisting of an epoxide, a polyisocyanate, a furane-resin-free phenolic resin, and mixtures thereof;
- (b) providing a thermosetting hardener;
- (c) providing a filler mixture containing:
  - (i) an inorganic high-temperature-resistant filler;
  - (ii) a heat-activatable swelling agent;

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- (iii) an adhesive;
- (iv) a micropore-forming, high-temperature-resistant filler; and
- (v) a grinding and/or anticaking agent; and
- (d) combining (a)-(c) to form the fiber-free molding composition.

Claim 22 (previously presented): The process of claim 21 further comprising mixing an emulsifier with the binder.

Claim 23 (previously presented): The process of claim 21 further comprising providing a blowing agent.

Claim 24 (previously presented): The process of claim 21 wherein the filler mixture has a pH of up to 7.5.

Claim 25 (previously presented): The process of claim 21 further comprising introducing the molding mixture into a mold to form a solid, fiber-free foam form.

Claim 26 (previously presented): The product of the process of claim 21.

Claim 27 (previously presented): The product of the process of claim 22.

Claim 28 (previously presented): The product of the process of claim 23.

Claim 29 (previously presented): The product of the process of claim 24.

Claim 30 (previously presented): The product of the process of claim 25.